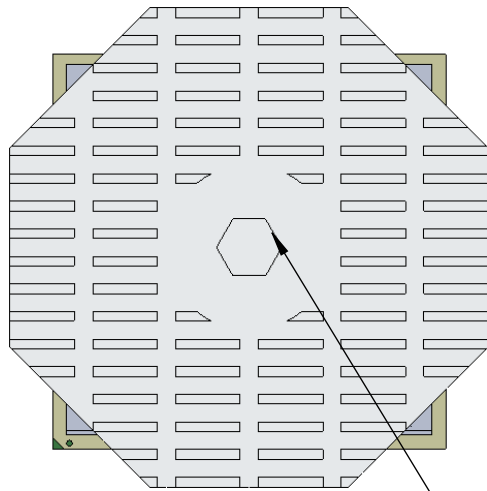


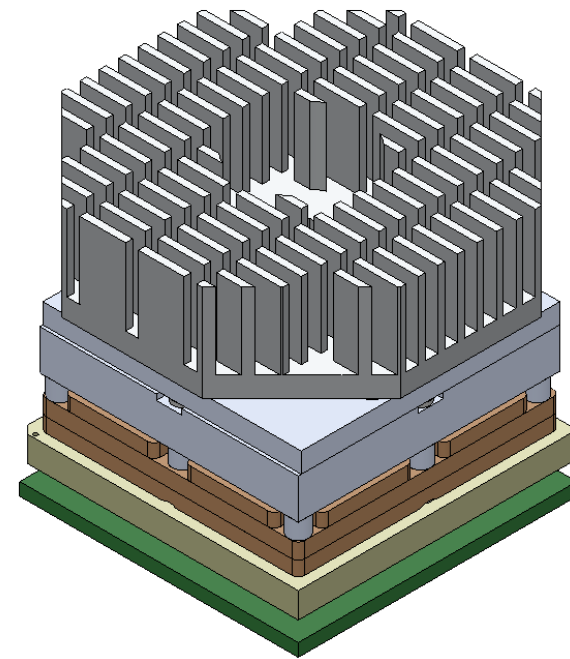
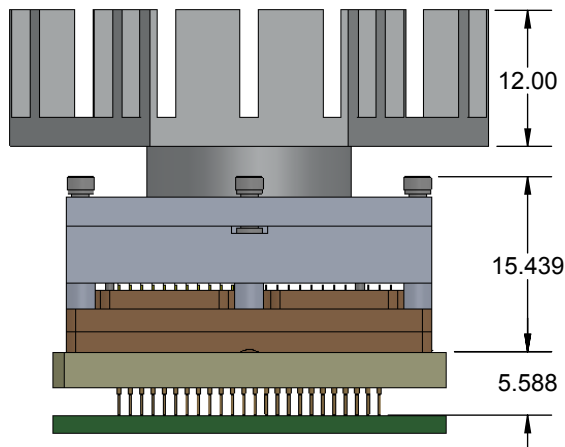
SBT BGA Socket - Direct mount, solderless

Features

- Wide temperature range (-55C to +180C)
- High current capability (up to 4A)
- Excellent signal integrity at high frequencies
- Low and stable contact resistance for reliable production yield
- Highly compliant to accommodate wide co-planarity variations
- Automated probe manufacturing enables low cost and short lead time




Recommended torque {TBD} in-lbs

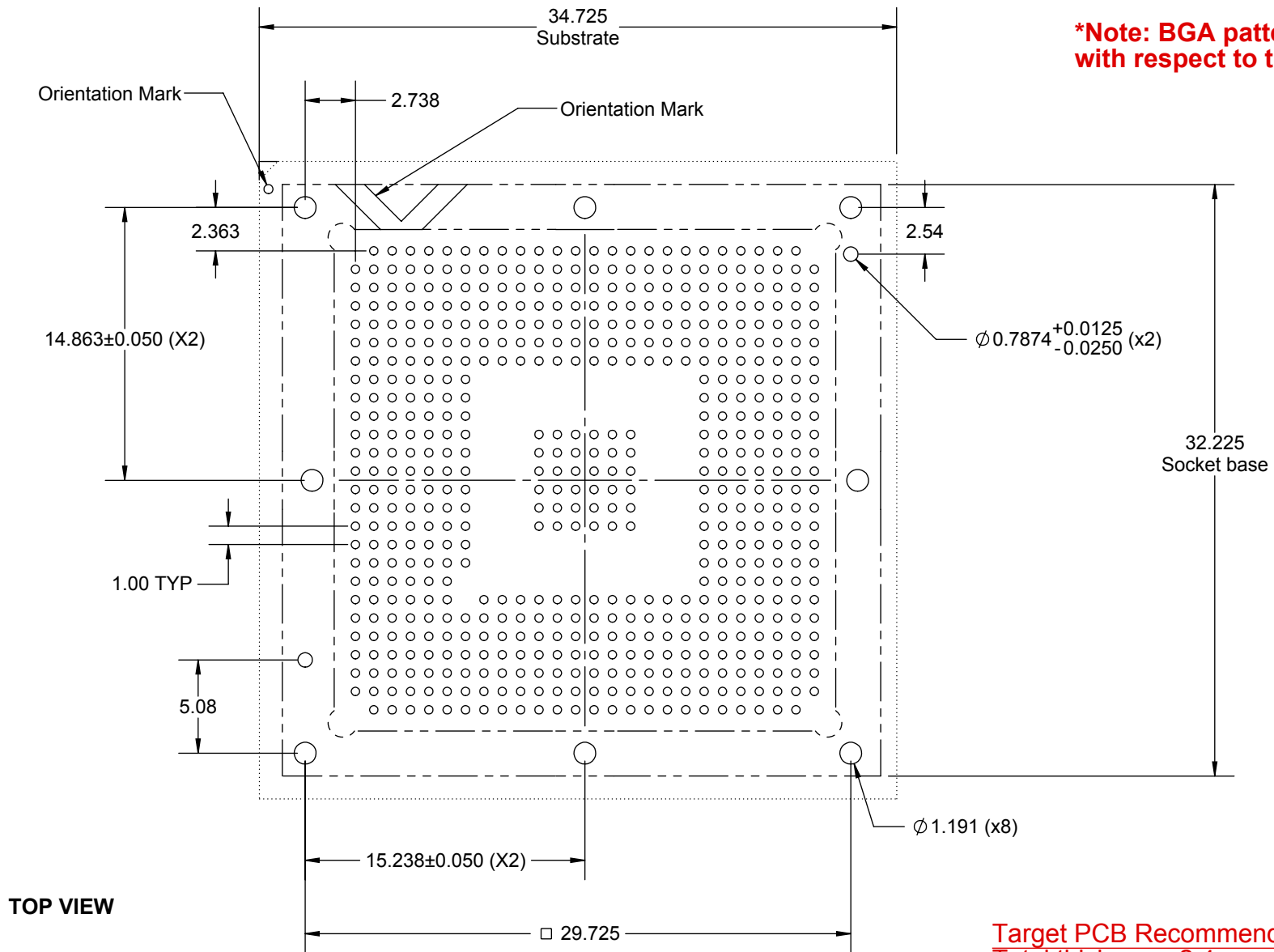


Description: SBT-BGA Socket

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

Tolerances: Hole diameters $\pm 0.03\text{mm}$ [± 0.001 "], Pitches (from true position) $\pm 0.025\text{mm}$ [± 0.001 "], substrate thickness tolerance $\pm 10\%$, all other tolerances $\pm 0.13\text{mm}$ [± 0.005 " unless stated otherwise. Materials and specifications are subject to change without notice.

 SBT-BGA-6022 Drawing Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com	Material: N/A Finish: N/A Weight: 54.39	STATUS: Released ENG: S. Faiz FILE: SBT-BGA-6022	SHEET: 1 OF 4 DRAWN BY: D. Hauer DATE: 09/13/12	REV. A SCALE: 3:2




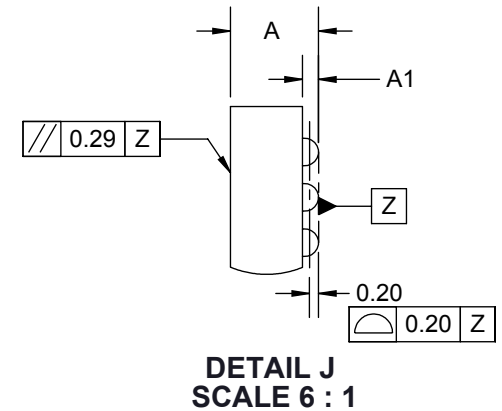
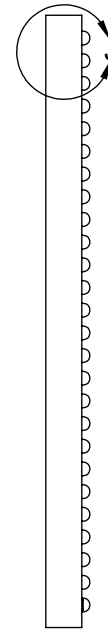
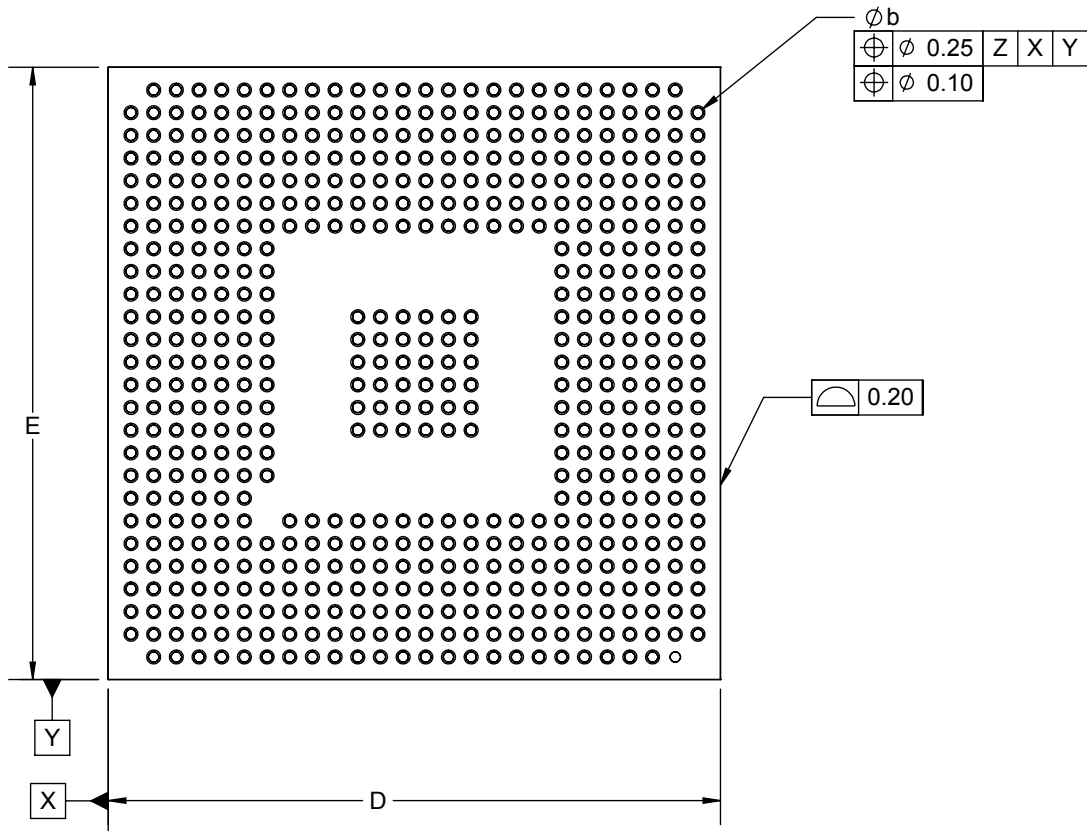
***Note: BGA pattern is not symmetrical with respect to the mounting holes.**

Target PCB Recommendations
 Total thickness: 2.4mm min.
 Plating: Gold or Solder finish
 PCB Pad height: Same or higher than solder mask

Description: Recommended PCB Layout

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.
 Tolerances: Hole diameters $\pm 0.03\text{mm}$ [$\pm 0.001"$], Pitches (from true position) $\pm 0.025\text{mm}$ [$\pm 0.001"$], substrate thickness tolerance $\pm 10\%$, all other tolerances $\pm 0.13\text{mm}$ [$\pm 0.005"$] unless stated otherwise. Materials and specifications are subject to change without notice.

 SBT-BGA-6022 Drawing Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com	Material: N/A Finish: N/A Weight: 54.39	STATUS: Released	SHEET: 2 OF 4	REV. A
		ENG: S. Faiz	DRAWN BY: D. Hauer	SCALE: 3:1
		FILE: SBT-BGA-6022	DATE: 09/13/12	




Array 26 x 26

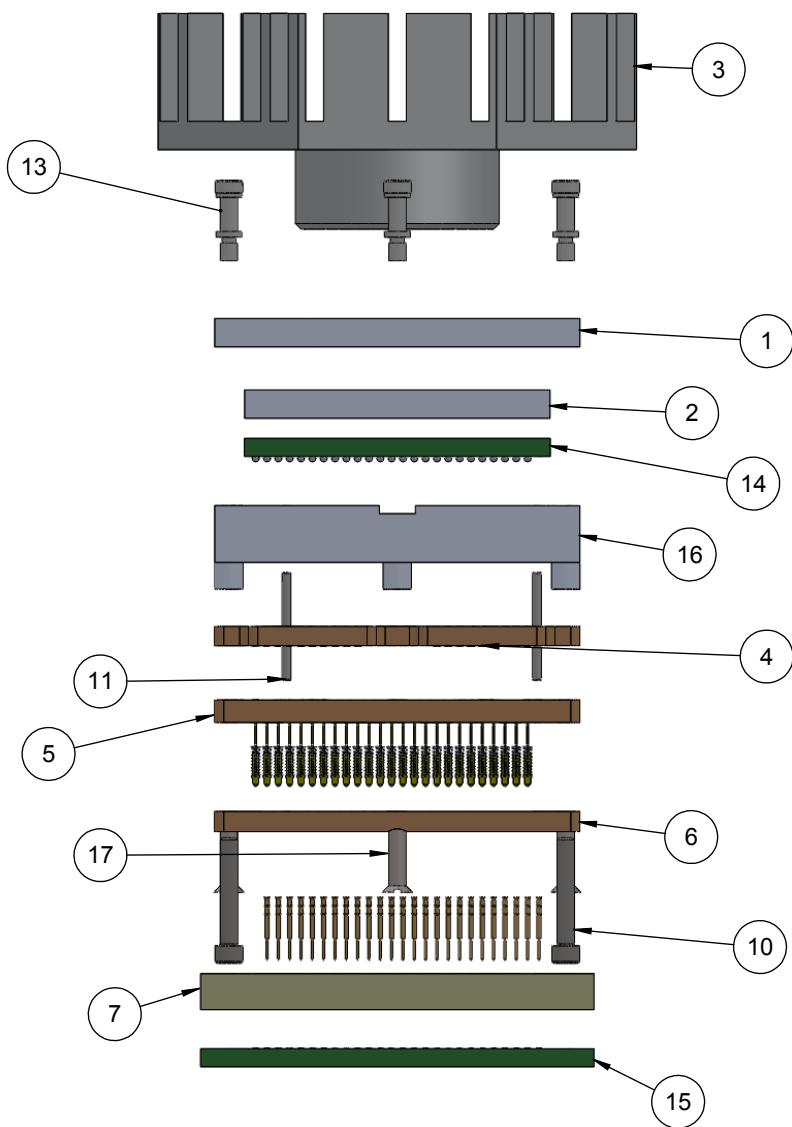
DIM	Minimum	Maximum
A	1.36	1.6
A1	0.45	0.55
b		0.70
D	27.00 BSC	
E	27.00 BSC	
e	1.00 BSC	
ARRAY SIZE	26 X 26	
PIN COUNT	562	

Dimensions are in millimeters.
 Interpret dimensions and tolerances per ASME Y14.5M-1994.
 Dimension b is measured at the maximum solder ball diameter, parallel to datum plane C.
 Datum C (seating plane) is defined by the spherical crowns of the solder balls.
 Parallelism measurement shall exclude any effect of mark on top surface of package.

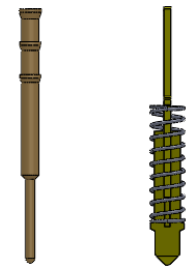
Description: Compatible BGA

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.
 Tolerances: Hole diameters $\pm 0.03\text{mm}$ [± 0.001 "], Pitches (from true position) $\pm 0.025\text{mm}$ [± 0.001 "], substrate thickness tolerance $\pm 10\%$, all other tolerances $\pm 0.13\text{mm}$ [± 0.005 "] unless stated otherwise. Materials and specifications are subject to change without notice.

 SBT-BGA-6022 Drawing Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com	Material: N/A Finish: N/A Weight: 54.39	STATUS: Released ENG: S. Faiz FILE: SBT-BGA-6022	SHEET: 3 OF 4 DRAWN BY: D. Hauer DATE: 09/13/12	REV. A SCALE: 3:1



ITEM NO.	DESCRIPTION	Material	QTY.
1	Socket Lid, 32.225 X 32.225	7075-T6 Aluminum Alloy	1
2	Compression Plate, 26.95 X 26.95	7075-T6 Aluminum Alloy	1
3	Heatsink Compression Screw	7075-T6 Aluminum Alloy	1
4	Floating Guide 26x26 array 1mm pitch BGA562	Semitron MDS 100	1
5	Middle Guide 26x26 array 1mm pitch BGA562	Semitron MDS 100	1
6	Bottom Guide 26x26 array 1mm pitch BGA562	Semitron MDS 100	1
7	Thru Hole Adaptor Board	FR4 Standard	1
8	Pogo Pin, 1mm Pitch SBT BGA pin	Material <not specified>	562
9	0.8mm pitch terminal pin	Brass 360 Half Hard	562
10	#0-80 X .375 LG, SOC HD CAP SCREW, ALLOY STL, BLK OXIDE	Alloy Steel	4
11	Dowel Pin, 1/32" x 3/8", SS	Chrome Stainless Steel	2
12	Solder Ball, ROHS Compliant 0.024" Dia	Sn96.5 Ag3.0 Cu0.5	562
13	#0-80 Shoulder Screw, 0.062" thread length	Stainless Steel (303)	4
14	Test Chip	Material <not specified>	1
15	Test PCB	Material <not specified>	1
16	Socket Base SBT 27x27mm Ni plated 0.375mm shift 1mm and 1.27 mm pitch IC	7075-T6 Aluminum Alloy	1
17	#0-80, 90 deg., head pin guide screw, Peek material 5.5715mm overall Length	PEEK unfilled	4




P-T122A(#10) and P-P151A(#9)
SCALE 6:1

Description: Socket Assy, Detail

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.
 Tolerances: Hole diameters ±0.03mm [±0.001"], Pitches (from true position) ±0.025mm [±0.001"], substrate thickness tolerance ±10%, all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

Rev	Date	Initials	Description
A	09/13/12	DH	Original
B	12/5/2013	BMF	Update for Manufacturability

 SBT-BGA-6022 Drawing Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com	Material: N/A	STATUS: Released	SHEET: 4 OF 4	REV. A
	Finish: N/A	ENG: S. Faiz	DRAWN BY: D. Hauer	SCALE: 3:2
	Weight: 54.39	FILE: SBT-BGA-6022	DATE: 09/13/12	